&TDK Multilayer Ceramic Chip Capacitors

C1608C0G1V153K080AC



TDK item description C1608C0G1V153KT****

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Dimensions in m

	Size
Length(L)	1.60mm ±0.10mm
Width(W)	0.80mm ±0.10mm
Thickness(T)	0.80mm ±0.10mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.70mm to 1.00mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PB)	0.80mm to 1.00mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.60mm to 0.80mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)

Electrical Characteristics		
Capacitance	15nF ±10%	
Rated Voltage	35VDC	
Temperature Characteristic	C0G(0±30ppm/°C)	
Q (Min.)	1000	
Insulation Resistance (Min.)	10000ΜΩ	

Other		
Soldering Method	Wave (Flow)	
	Reflow	
AEC-Q200	No	
Packing	Punched (Paper)Taping [180mm Reel]	
Package Quantity	4000pcs	

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Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

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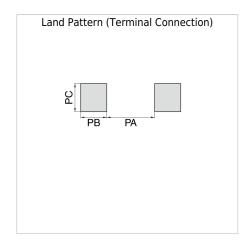
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Associated Images



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